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501.39932X00
Response Under 37 CFR 1.116
Expedited Procedure
Group No. 2811

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): NOGUCHI et al.

Serial No.: 09/825,946

Filed: April 5, 2001

For: SEMICONDUCTOR INTEGRATED CIRCUIT DEVICE AND
FABRICATION METHOD FOR SEMICONDUCTOR
INTEGRATED CIRCUIT DEVICE

Title

Group: 2811

Examiner: H. Vu

AMENDMENT AFTER FINAL REJECTION

Assistant Commissioner
for Patents
Washington, D.C. 20231

APR 21 2003
RECEIVED
TECHNOLOGY CENTER 2800

APR 16, 2003

Sir:

In response to the Office Action of November 20, 2003, please amend the
above-identified application as follows:

IN THE CLAIMS:

Please cancel Claims 24 and 28.

Please amend Claim 20, 25, 26, 29, - 31 as follows:

20. (twice amended) A method of fabricating a semiconductor integrated circuit
device comprising:

(a) providing a semiconductor substrate having a first main surface,